

Products

▣ Laser Processing Machines

[▶ Product List](#)

▾ Product Features

[▶ Lineup](#)
[▶ 2D Laser Processing Machines](#)
[▶ 3D Laser Processing Machines](#)
[▶ Laser Drilling Machines](#)
[▶ Large Size Laser Processing Machines](#)
[▶ Automation for Laser](#)
[▶ Software Features](#)
[▶ Events](#)

Lineup

[▶ 2D Laser Processing Machines](#)
[▶ 3D Laser Processing Machines](#)
[▶ Laser Drilling Machines](#)
[▶ Large Size Laser Processing Machines](#)
[▶ Automation for Laser](#)

Laser Drilling Machines

[▾ GTW5 Series](#)
[▾ GTF4 Series](#)
[▾ GTW5-UVF20 Series](#)

Laser Drilling Machines

Delivers high precision laser drilling at ultra high speeds.

Mitsubishi Electric laser drilling machines serve as a platform for state-of-the-art technologies around the world.

We develop, design and manufacture.

This comprehensive approach provides high reliability.

L GTW5 Series


[▶ Product Specifications](#)

2-beam-2-panel model

All-round model

Full fθ lens lineup for this model enables its application to various types of processes from copper direct drilling, resin direct drilling and small-diameter hole drilling.

Industry's top-level productivity

New control technology "Synchrom", equipped as standard function, achieves overwhelming productivity, stable processing quality and high positioning accuracy.

Small diameter drilling that fascinates the world

Mitsubishi Electric's original optical technology allows the laser to drill holes less than 40μm in diameter, which has been considered too challenging for CO₂ lasers.

[page top](#)

L GTF4 Series



4-beam-2-panel model

Package substrate drilling machine

Targeting at package substrate processing, this 4-beam machine realizes high productivity, stable quality and accurate positioning.

Overwhelming productivity

Mitsubishi Electric's original optics for simultaneous 4-beam drilling and

"5350UM ", laser oscillator exclusive for package substrate processing, achieve the industry's top-class productivity.

High positioning accuracy

The newly developed galvano scanner "2700GL2" and ultra rigid machine frame realize extremely high positioning accuracy.

[page top](#)

GTW5-UVF20 Series



2-beam-2-panel model

Flexible substrate drilling machine

The "UV laser oscillator" with a laser wavelength of 355nm, suited for the processing of Polyimide which is the main material of flexible substrates, realizes consistent processing quality.

High speed trepanning

Mitsubishi Electric's original galvano scanner, newly developed control technology "Synchrom" and high speed UV laser oscillator help bring higher productivity with consistent quality.

Stable mass-production

Equipped with a Reel-to-Reel (RtoR) sheet transfer device applicable to 250/260mm wide sheets. Delivers stable high-volume production on rolled materials.

[page top](#)

[▶ 2D Laser Processing Machines](#)
[▶ 3D Laser Processing Machines](#)
[▶ Laser Drilling Machines](#)

[▶ Large Size Laser Processing Machines](#)
[▶ Automation for Laser](#)

[page top](#)

FA Products

▶ Edge Computing Products

- ▶ Industrial Computer MELIPC
- ▶ Edge Computing Software

▶ Controllers

- ▶ Programmable Controllers MELSEC
- ▶ Simple Application Controllers
- ▶ Motion Controllers
- ▶ Computerized Numerical Controllers(CNCs)
- ▶ Data logging analyzer-MELQIC

▶ FA Sensor

- ▶ FA Sensor MELSENSOR

▶ Drive Products

- ▶ AC Servos-MELSERVO
- ▶ Inverters-FREQROL
- ▶ Geared Motors

▶ Visualization

- ▶ Human-Machine Interfaces(HMIs)-GOT
- ▶ SCADA

▶ Robots

- ▶ Industrial/Collaborative Robots-MELFA

▶ Low-voltage Power Distribution Products

- ▶ Low-voltage Circuit Breakers
- ▶ Contactors and Motor Starters

▶ Power Monitoring Products

- ▶ Power Management Meters
- ▶ Energy Saving Supporting Devices

▶ Medium-voltage Power Distribution Products

- ▶ Protection Relays

▶ Processing Machines

- ▶ Laser Processing Machines
- ▶ Electrical Discharge Machines
- ▶ Electron Beam Machines

